



Product Change Notification: CAAN-10DTK0161

Date:

23-Jun-2025

Product Category:

Wireless Modules

Notification Subject:

CCB 7215 Initial Notice: Qualification of MMT as an additional assembly site for PIC32CX5109BZ31048-V/ZWX and PIC32CX5109BZ31048T-V/ZWX catalog part numbers (CPN) available in 48L VQFN (6x6x0.9mm) wettable flank packages.

Affected CPNs:

[CAAN-10DTK0161_Affected_CPN_06232025.pdf](#)

[CAAN-10DTK0161_Affected_CPN_06232025.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for PIC32CX5109BZ31048-V/ZWX and PIC32CX5109BZ31048T-V/ZWX catalog part numbers (CPN) available in 48L VQFN (6x6x0.9mm) wettable flank packages.

Pre and Post Summary Changes:

	Pre Change	Post Change	
Assembly Site	ASE Group Chung-Li (ASCL)	ASE Group Chung-Li (ASCL)	Microchip Technology Thailand (Branch) (MMT)
Wire Material	CuPdAu	CuPdAu	CuPdAu

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: November 21, 2024: Issued initial notification.

January 24, 2025: Re-issued initial notification to update the die attach material from QMI519 to 3280NP.

June 23, 2025: Re-issued initial notification to update Qual Plan. Updated the estimated qualification completion date and the time table summary.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CAAN-10DTK0161 Qual Plan.pdf

PCN_CAAN-10DTK0161 Pre and Post Change Summary.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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CAAN-10DTKO161 - CCB 7215 Initial Notice: Qualification of MMT as an additional assembly site for PIC32CX5109BZ31048-V/ZWX and PIC32CX5109BZ31048T-V/ZWX catalog part numbers (CPN) available in 48L VQFN (6x6x0.9mm) wettable flank packages.

Affected Catalog Part Numbers (CPN)

PIC32CX5109BZ31048-V/ZWX

PIC32CX5109BZ31048T-V/ZWX

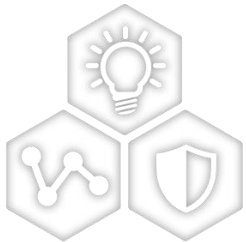
CCB 7215

Pre and Post Change Summary

PCN #: CAAN-10DTKO161



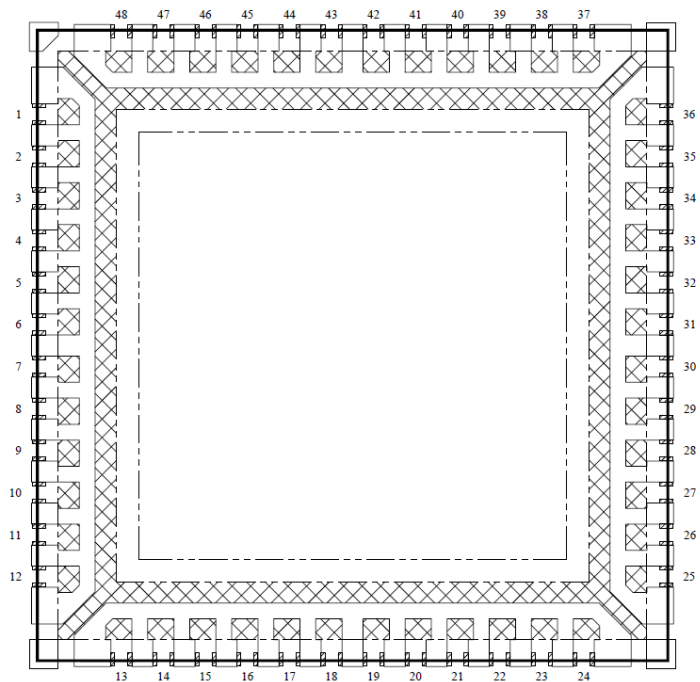
A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



SMART | CONNECTED | SECURE

LEAD FRAME COMPARISON

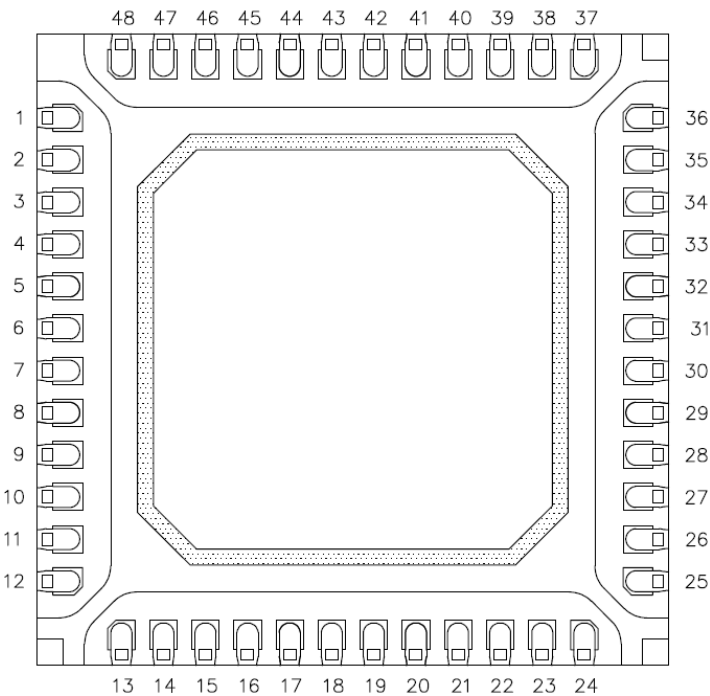
ASCL



Note: Not to scale

Wire Material	CuPdAu
Lead Frame Material	C194
Lead-Frame Paddle Size	173x173 mils

MMT



Note: Not to scale

Wire Material	CuPdAu
Lead Frame Material	C194
Lead-Frame Paddle Size	181x181 mils



QUALIFICATION PLAN SUMMARY

PCN #: CAAN-10DTKO161

**Date:
June 10, 2025**

**Qualification of MMT as an additional assembly site for
PIC32CX5109BZ31048-V/ZWX and PIC32CX5109BZ31048T-V/ZWX
catalog part numbers (CPN) available in 48L VQFN (6x6x0.9mm)
wetable flank packages.**

Purpose:

Qualification of MMT as an additional assembly site for
 PIC32CX5109BZ31048-V/ZWX and PIC32CX5109BZ31048T-V/ZWX
 catalog part numbers (CPN) available in 48L VQFN (6x6x0.9mm)
 wettable flank packages.

CCB No.:

7215

<u>Misc.</u>	Assembly site	MMT
	BD Number	BDM-002713 Rev. M
	MP Code (MPC)	SG4069ZWXA00
	Part Number (CPN)	PIC32CX5109BZ31048-V/ZWX
	MSL information	MSL1@260°C
	Assembly Shipping Media	Tray
	Base Quantity Multiple (BQM)	490
	Reliability Site	MPHIL
<u>Lead-Frame</u>	Paddle size	181x181 mils
	Material	C194
	DAP Surface Prep	Ag ring with roughening
	Treatment	BOT
	Process	Etched
	Lead-lock	Yes
	Part Number	10104814
	Lead Plating	Matte Tin
<u>Bond Wire</u>	Material	CuPdAu
<u>Die Attach</u>	Part Number	3280NP
	Conductive	Yes
<u>MC</u>	Part Number	G700LTD
<u>PKG</u>	Package Type	VQFN-WFS
	Pin/Ball Count	48
	PKG width/size	6x6x0.9 mm

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Special Instructions
Standard Pb-free Solderability	J-STD-002D ; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5		MMT	Standard Pb-free solderability is the requirement.
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5		MMT	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5		5		MMT	30 bonds from a min. 5 devices.
Physical Dimmensions	Measure per JESD22 B100 and B108	10	0	3	30		5		MPHL	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5		MMT	
HTSL (High Temp Storage Life)	JESD22-A103. +175 C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25C and hot temp.	45	5	1	50	0	10	MPHL	MPHL	
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. MSL 1@260°C	231	15	3	738	0	15	MPHL	MPHL	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A110. +130°C/85% RH for 96 hours Electrical test pre and post stress at +25°C, +105°C and +125°C.	77	5	3	246	0	10	MPHL	MPHL	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A118. +130°C/85% RH for 96 hrs Electrical test pre and post stress at +25°C	77	5	3	246	0	10	MPHL	MPHL	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -55°C to +150°C for 1000 cycles. Electrical test pre and post stress at +105°C and +125°C; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	MPHL	MPHL	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.